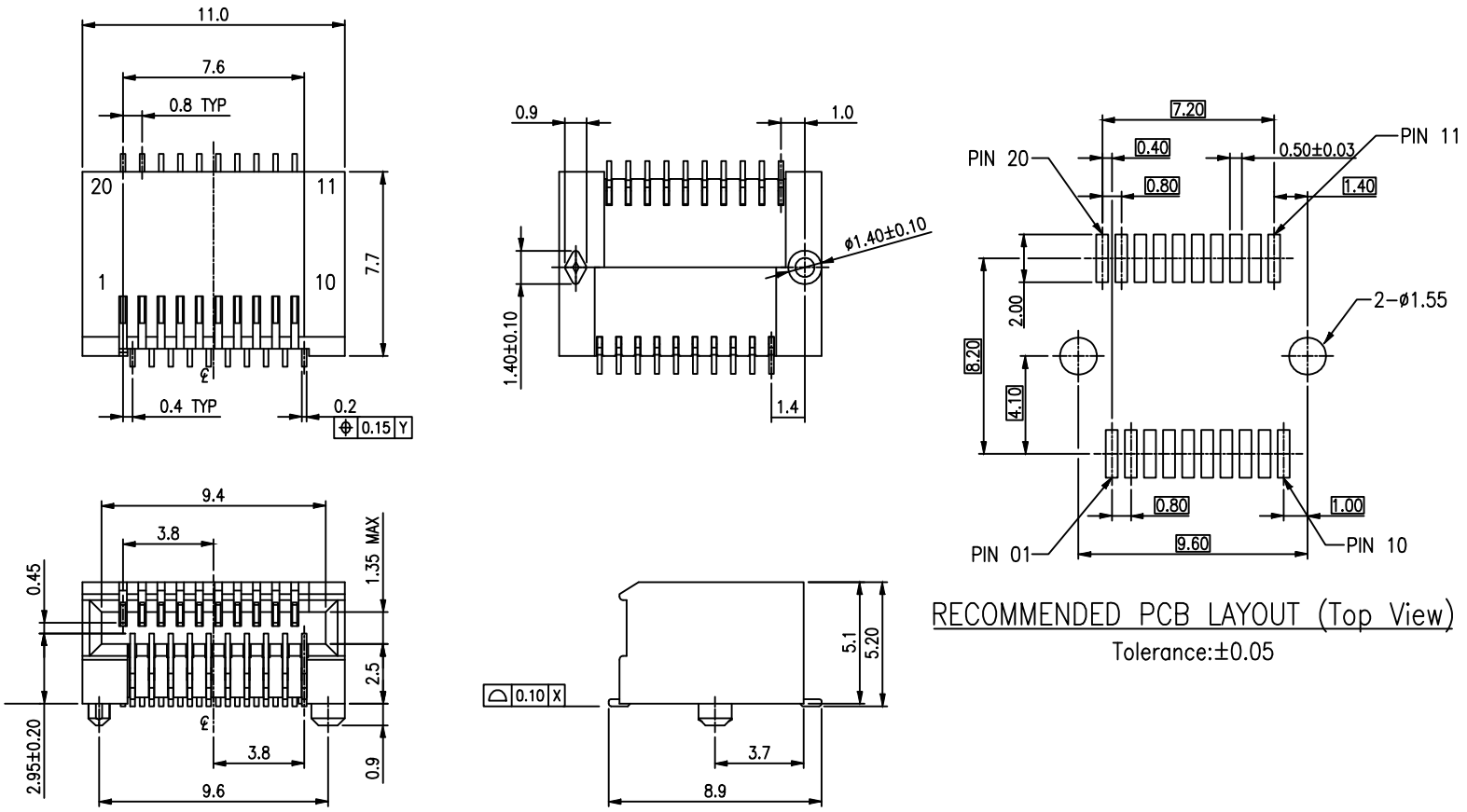
# Mechanical:

| REV. | ECN NO. | DESCRIPTION | DATE | APPD |
|---|---|---|---|---|
| A | REL | | 2012/08/27 | |




RECOMMENDED PCB LAYOUT (Top View)

Tolerance:±0.05

NOTE:

MATERIAL:

1. TERMINAL: C5210-EH T=0.20+/-0.01
2. HOUSING: LCP MG350 UL 94V-0. COLOR: BLACK

PLATING:

1. 1.27um MIN. Ni UNDERPLATING.
2. 0.76um MIN. MATTE TIN PLATING ON SMT.
3. 0.38um OR 0.76um MIN. GOLD PLATING ON CONTACT AREA.

MECHANICAL REQUIREMENT:

1. DURABILITY: 100 CYCLES MIN.
2. INSERTION AND EXTRACTION FORCE: 40N MAX & 12.5N MAX

ENVIRONMENTAL:

1. CONTACT RESISTANCE: 30 MILLIOHMS MAX INITIAL.
2. DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.
3. OPERATION: -40 ° C~+85 ° C.
4. STORAGE: -55 ° C~+105 ° C.
5. REFLOW SOLDERING TEMPERATURE:255~265 ° MAXIMUM FOR 5~10 SECONDS.

RoHS 2011/65/EU

| | | | |
|---|---|---|---|
| X:X | APPD: | LINK-PP INT'L TECHNOLOGY CO., LIMITED | |
| X:XX ±0.25 | CHKD: | | |
| X:XXX ±0.15 | DR: James | TITLE: SFP+ 1X1 CONNECTOR | |
| ANGLES ±1° | UNIT: mm | PART NO.: LP11F003 | |
| | SCALE: 2/1 | SHEET: 1/1 | REV: A |
| | | | DWG NO.: LP12082711 |